

IN THE ABSTRACT

Please replace the Abstract of the Disclosure with the rewritten Abstract of the Disclosure located on a separate sheet attached at the end of the amendment.

IN THE SPECIFICATION

Please replace the paragraph beginning on page ¹~~2~~, line ¹⁹~~16~~ and continuing to page 2 with the following rewritten paragraph.

AI -- As shown in FIG. 1, the conventional one system module 100 includes a case 101 having a rectangular parallelepiped-shaped configuration, and power pins 102 and signal pins 103 which are arranged adjacent to both long edges on an upper surface of the case 101. Here, the power pins 102 includes three phase U, V and W pins for being connected with a motor (not shown) and pins for supplying DC power (for example, DC 310V) which is obtained by rectifying AC power (for example, AC 220V). The signal pins 103 are used for interfacing a microcomputer (micom) and other sensors. In FIG. 1, the drawing reference numeral 101t represents an engaging protrusion where a heat sink (not shown) is attached to the case 101.--

Please replace the paragraph beginning on page 3, line 23, with the following rewritten paragraph:

A2
--On the other hand, the conventional one system module constructed as mentioned above has a double-layered structure in which the signal board 300 is superposed on the power board 200 inside the case 101. In this double-layered structure, since the power pins 102 and the signal pins 103 are simultaneously arranged adjacent to the same edge on the upper surface of the case 101, a problem is caused in that assemblage is deteriorated when the one system module is applied to an appliance. Further, because all the power pins 102 are arranged adjacent to only one edge on the upper surface of the case 101, an entire size of the one system module is increased.--

Please replace the paragraph beginning on page 7, line 6, and continuing to page 8, with the following rewritten paragraph:

A3
-- Referring to FIGs. 5 and 6, one system module 500 for an electric/electronic appliance in accordance with an embodiment of the present invention includes a case 501 which constitutes a body of the one system module 500, power pins 502 and signal pins 503 which are disposed adjacent to three edges on a surface of the case 501 in a manner such that substantially a U-shaped arrangement is obtained, a

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power board 504 which is located inside the case 501 and electrically connected with the power pins 502, and a signal board 505 which is located inside the case 501 and electrically connected with the signal pins 503. Here, in the preferred embodiment of the present invention, at least two corner portions among four corner portions of the case 501, which two corner portions are opposite to each other in a diagonal direction, are defined with engaging holes 501h, respectively, through which the case 501 and a heat sink 510 are coupled with each other. Moreover, a plurality of connecting pins 504p are formed on the power board 504 so as to electrically connect the power board 504 and the signal board 505 with each other, and a plurality of inserting holes through which the connecting pins 504p are inserted, respectively, are defined in the signal board 505. In this regard, a person skill in the art will readily recognize that the connecting pins 504p and the inserting holes can be formed and defined vice versa. Namely, the connecting pins 504p can be formed on the signal board 505, and the inserting holes can be defined in the power board 504.--

Please replace the paragraph beginning on page 8, line 17, with the following rewritten paragraph:

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--As described above, by the one system module for an